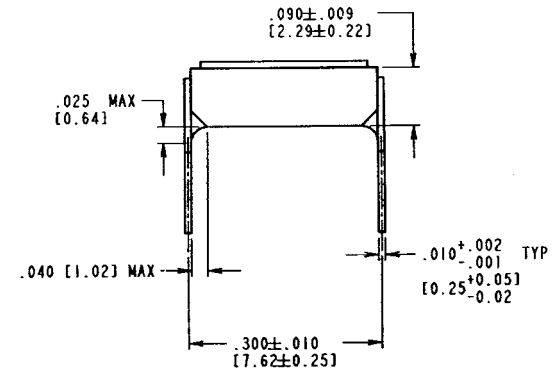
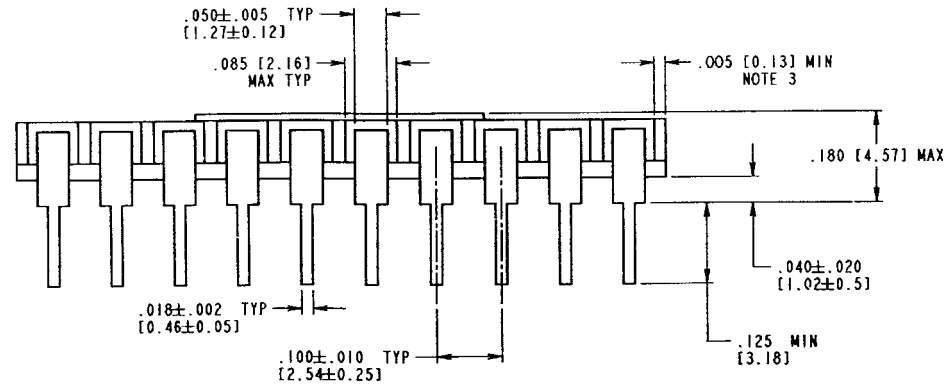
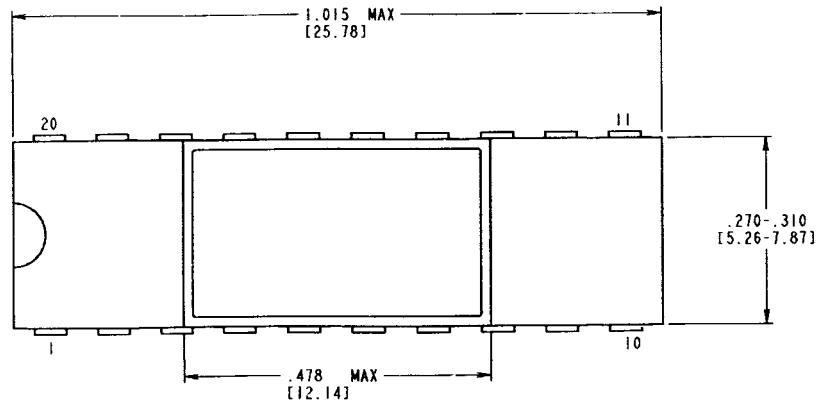


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW PER NEW STANDARD.	10259	02/16/94	DEG/TP
F	.085 MAX WAS .080 ± .008; .270-.310 WAS .290 ± .003.	10472	07/01/94	DEG/TP



NOTES: UNLESS OTHERWISE SPECIFIED.

- LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 200 MICROINCHES/5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
 - 50 MICROINCHES/1.27 MICROMETERS MINIMUM GOLD OVER 50 TO 350 MICROINCHES/1.27 TO 8.89 MICROMETERS NICKEL UNDERPLATE.
- LEAD FINISH, NICKEL UNDERPLATE AND BASIS METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510.
- DIMENSION .005 IN/0.13mm MINIMUM SHALL BE MEASURED FROM THE EDGE OF THE FURTHEST EXTENSION OF THE METAL PAD OR LEAD.
- REFERENCE JEDEC REGISTRATION MS-015, VARIATION AE, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

MIL/AERO
CONFIGURATION CONTROL

MIL-M-38510
CONFIGURATION CONTROL

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION			
DRM <i>Drayce Grady</i>	02/16/94	2000 Semiconductor Drive, Santa Clara, CA 95052-8000			
DFTG. CH. <i>D. J. [Signature]</i>	7-7-94	DIP, SIDEBRAZED CERAMIC, 20 LEAD			
ENGR. SUP. <i>D. J. [Signature]</i>	7-7-94				
APPROVAL		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-D20A	F
PROJECTION 		DO NOT SCALE DRAWING		SHEET 1 of 1	